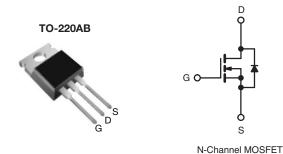


Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	600				
R _{DS(on)} (Ω)	V _{GS} = 10 V	2.2			
Q _g (Max.) (nC)	23				
Q _{gs} (nC)	5.4				
Q _{gd} (nC)	11				
Configuration	Single				



FEATURES

• Low Gate Charge Qq Results in Simple Drive Requirement



 Improved Gate, Avalanche and Dynamic dV/dt RoHS Ruggedness

- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective Coss Specified
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptable Power Supply
- High Speed Power Switching

TYPICAL SMPS TOPOLOGY

• Single Transistor Flyback

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRFBC30APbF		
Lead (FD)-life	SiHFBC30A-E3		
SnPb	IRFBC30A		
SIFD	SiHFBC30A		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	600	V	
Gate-Source Voltage			V_{GS}	± 30	V	
Continuous Drain Current	V _{GS} at 10 V	$T_C = 25 ^{\circ}\text{C}$ $T_C = 100 ^{\circ}\text{C}$		3.6	А	
Continuous Drain Current	V _{GS} at 10 V	_C = 100 °C	I _D	2.3		
Pulsed Drain Current ^a			I _{DM}	14		
Linear Derating Factor				0.69	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	290	mJ	
Repetitive Avalanche Current ^a			I _{AR}	3.6	Α	
Repetitive Avalanche Energy ^a			E _{AR}	7.4	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$			P_{D}	74	W	
Peak Diode Recovery dV/dt ^c			dV/dt	7.0	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	00	
Soldering Recommendations (Peak Temperature) for 10 s			-	300 ^d	°C	
Mounting Toyour	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque			-	1.1	N·m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Starting T_J = 25 °C, L = 41 mH, R_q = 25 Ω , I_{AS} = 3.6 A (see fig. 12).
- c. $I_{SD} \le 3.6$ A, $dI/dt \le 170$ A/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRFBC30A, SiHFBC30A



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	1.7		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.67	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		-	4.5	V
Gate-Source Leakage	I _{GSS}	\	V _{GS} = ± 30 V		-	± 100	nA
Zero Gate Voltage Drain Current	lnoo	V _{DS} = 600 V, V _{GS} = 0 V		-	-	25	μА
Zero date voltage Brain Gunent	I _{DSS}	$V_{DS} = 480 \text{ V}$	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	$I_D = 2.2 A^b$	-	-	2.2	Ω
Forward Transconductance	9 _{fs}	V _{DS} =	$50 \text{ V}, I_D = 2.2 \text{ A}^b$	2.1	-	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$		510	-	- -
Output Capacitance	C _{oss}				70	-	
Reverse Transfer Capacitance	C_{rss}	f = 1.0 MHz, see fig. 5		-	3.5	-	
Output Capacitance	C _{oss}		$V_{DS} = 1.0 \text{ V}, f = 1.0 \text{ MHz}$	-	730	-	pF
Output Capacitance		$V_{GS} = 0 V$	$V_{DS} = 480 \text{ V}, f = 1.0 \text{ MHz}$	-	19	-	
Effective Output Capacitance	C _{oss} eff.		V _{DS} = 0 V to 480 V ^c		31	-	
Total Gate Charge	Q_g			-	-	23	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 3.6 \text{ A}, V_{DS} = 480 \text{ V}$ see fig. 6 and 13 ^b	-	-	5.4	
Gate-Drain Charge	Q _{gd}		3 7 7 7	-	-	11	
Turn-On Delay Time	t _{d(on)}				9.8	-	
Rise Time	t _r	V _{DD} =	300 V, I _D = 3.6 A,	-	13	-]
Turn-Off Delay Time	t _{d(off)}		$R_{\rm g} = 12 \ \Omega, \ R_{\rm D} = 82 \ \Omega, \ {\rm see} \ {\rm fig.} \ 10^{\rm b}$		19	-	- ns
Fall Time	t _f			-	12	-	
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	3.6	
Pulsed Diode Forward Current ^a	I _{SM}			-	-	14	A
Body Diode Voltage	V_{SD}	T _J = 25 °C, I _S = 3.6 A, V _{GS} = 0 V ^b		-	-	1.6	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 3.6 A, dl/dt = 100 A/μs ^b		-	400	600	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	1.1	1.7	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L				1 - \	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %.
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

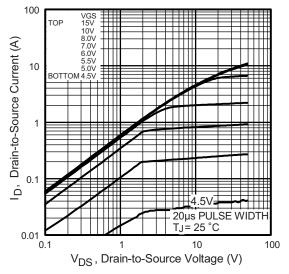


Fig. 1 - Typical Output Characteristics

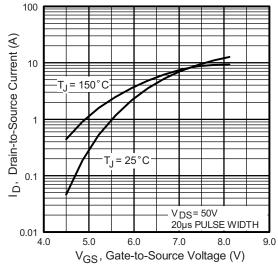


Fig. 3 - Typical Transfer Characteristics

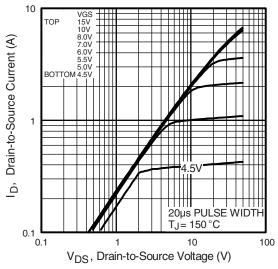


Fig. 2 - Typical Output Characteristics

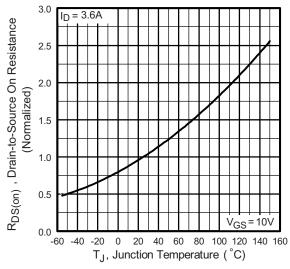


Fig. 4 - Normalized On-Resistance vs. Temperature



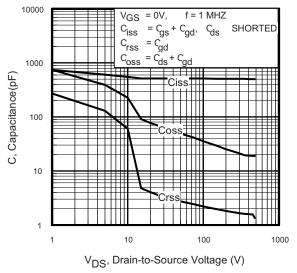


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

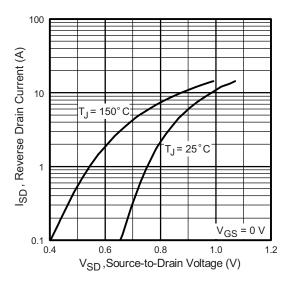


Fig. 7 - Typical Source-Drain Diode Forward Voltage

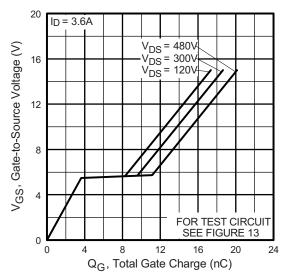


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

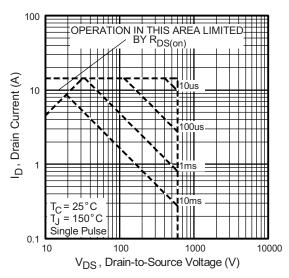


Fig. 8 - Maximum Safe Operating Area

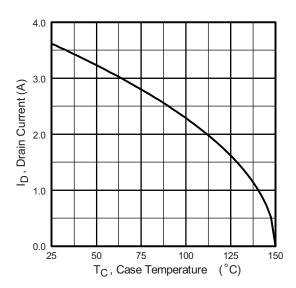


Fig. 9 - Maximum Drain Current vs. Case Temperature

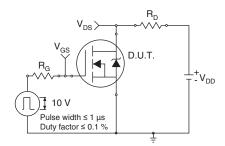


Fig. 10a - Switching Time Test Circuit

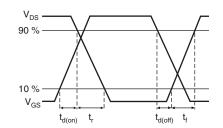


Fig. 10b - Switching Time Waveforms

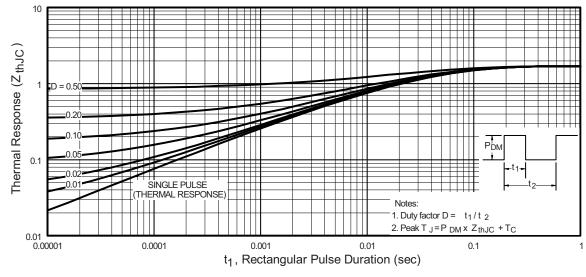


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

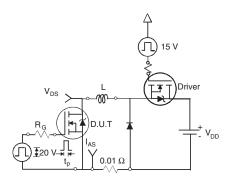


Fig. 12a - Unclamped Inductive Test Circuit

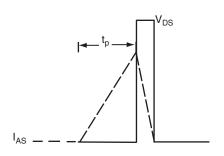


Fig. 12b - Unclamped Inductive Waveforms



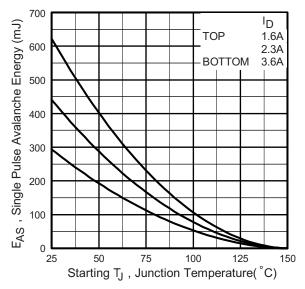


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

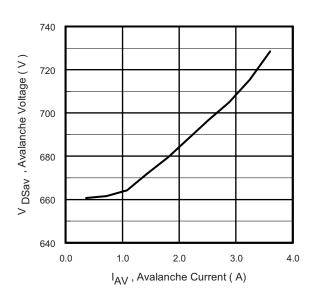


Fig. 12d - Typical Drain-to-Source Voltage vs.
Avalanche Current

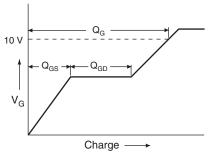


Fig. 13a - Basic Gate Charge Waveform

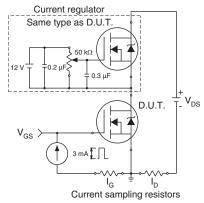
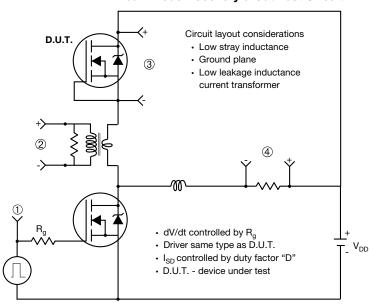


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



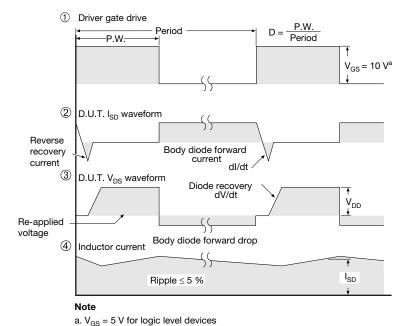


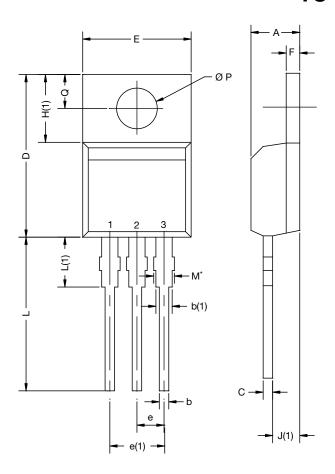
Fig. 14 - For N-Channel

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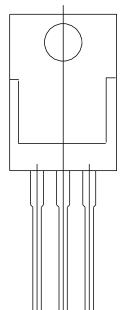
TO-220-1



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.14	4.70	0.163	0.185	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.73	0.045	0.068	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	0.43	1.40	0.017	0.055	
H(1)	6.10	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.59	3.00	0.102	0.118	
ECN: X15-0003-Rev. A, 19-Jan-15 DWG: 6031					

Notes

- M* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM
- Outline conforms to JEDEC[®] outline TO-220AB with exception of dimension F



Revison: 19-Jan-15 1 Document Number: 66542



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Revision: 02-Oct-12 Document Number: 91000

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